

Willkommen bei O-Leading

O-Leading ist bestrebt, Ihr One-Stop-Lösungspartner in der EMS-Lieferkette zu sein, einschließlich Leiterplattendesign, Leiterplattenherstellung und Leiterplattenbestückung (PCB Assembly, PCBA) Wir können vom schnellen Drehungsprototyp zur mittleren u. Massenproduktion stützen.

Generell sind unsere globalen Kunden von unseren Dienstleistungen sehr beeindruckt: Schnelle Reaktion, wettbewerbsfähiger Preis und Qualitätsverpflichtung. Wertvolleren technischen Service und Gesamtlösung zu bieten, ist der Weg, der O nach vorne weist.

Mit Blick auf die Zukunft wird sich O-Lead wie immer auf die Innovation und Entwicklung der Technologie für die Elektronikfertigung konzentrieren und beharrliche Anstrengungen unternehmen, um erstklassige Dienstleistungen aus einer Hand für PCB und PCBA zu erbringen und mehr Wert für unsere Kunden zu schaffen.

BITTE KLICKEN SIE HIER FÜR WEITERE INFORMATIONEN: [Hochwertige Leiterplatten China](#)

Produktbeschreibung

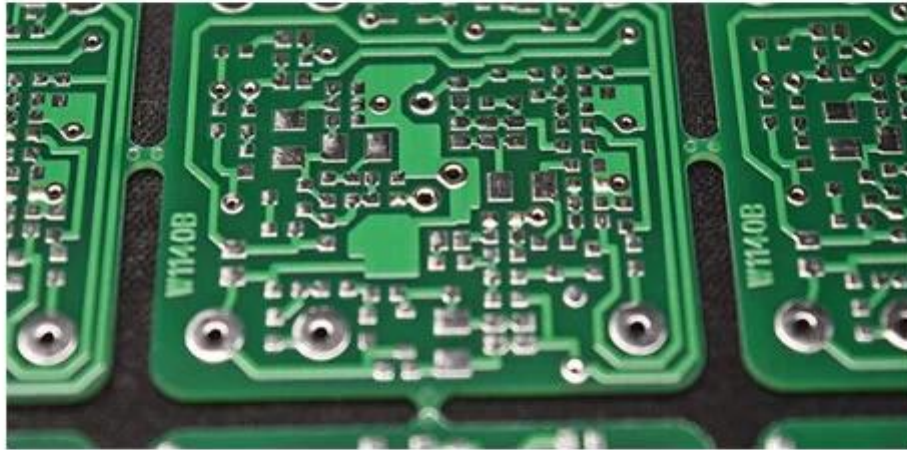
| | | | |
|-----------------------|--|------------------------|----------------------------|
| Herkunftsart | Guangdong China (Festland) | Markenname | O-führend |
| Basismaterial | FR-4, Aluminium | Kupferdicke | 0,5 Unzen-5 Unzen |
| Mindest. Lochgröße | 0,2 mm | Mindest. Linienbreite | 0,2 mm |
| Oberflächenveredelung | Immersiongold, OSP, bleifreies HASL | Brettstärke | 0,1-5 mm |
| anwendbar auf | LED, Handy, Klimaanlage, Waschmaschinen | Charakter | Industriesteuerungsplatine |
| Zertifikate | ISO9001, UL, RoHS, SGS | Q / CTN | 10PCS-100PCS |
| Gewicht | 0,01 kg - 5 kg | MOQ | 10 Stück |
| Modellnummer | Power Bank Leiterplattenbestückung pcba Hersteller | Mindest. Zeilenabstand | 0,2 mm |
| Farbe | blau, rot, grün, schwarz.gelb | Preis | \$ 0.1- \$ 10 |
| Design-Typ | Kundenanforderung | Größe | 0,01 m3 bis 10 m3 |

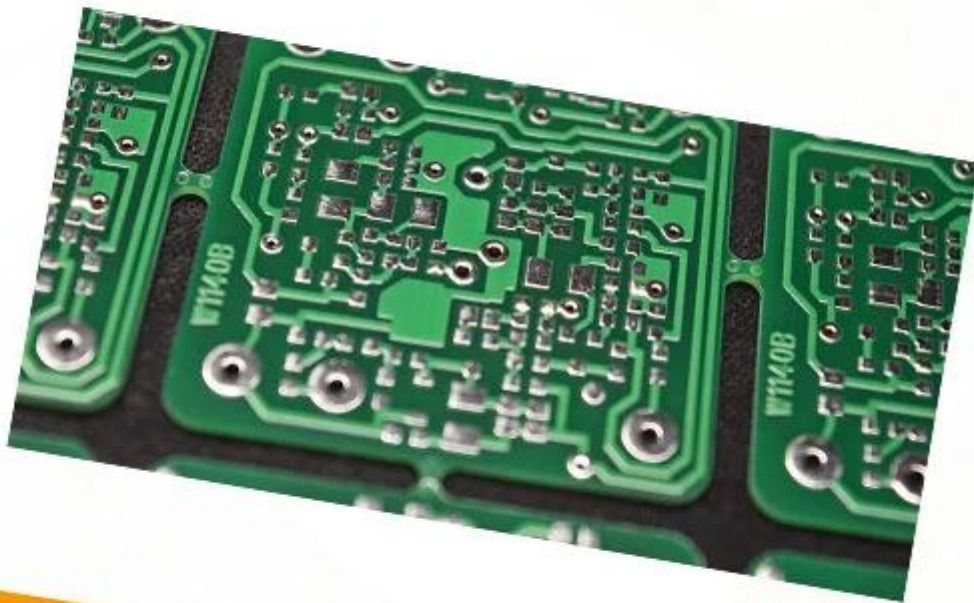
Produktionsfähigkeit

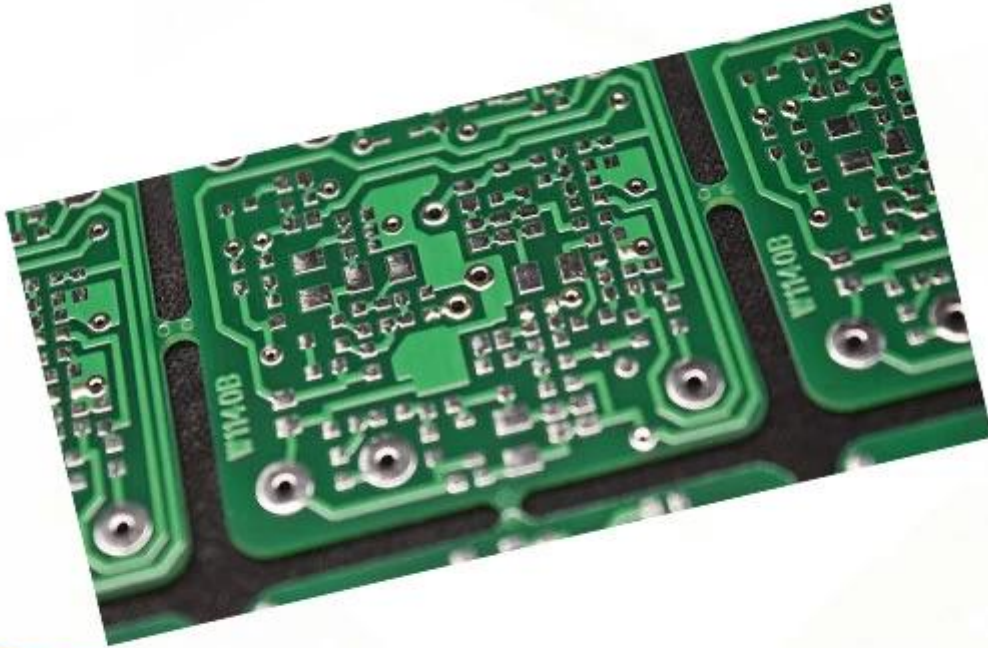
16 Jahre professionelle OEM-Leiterplattenherstellung

| Artikel | 2014 | | 2015 ~ 2016 | | 2017 ~ 2018 | |
|-------------------------------|---------|------------|-------------|------------|-------------|------------|
| | Volumen | Stichprobe | Volumen | Stichprobe | Volumen | Stichprobe |
| Ebenenzahl | 32 | 42 | 38 | 44 | 42 | 48 |
| Min. Linie / Abstand (µm) | 50/50 | 40/45 | 40/45 | 40/40 | 35/40 | 35/35 |
| Min. Bohrung Durchmesser (mm) | 0,15 | 0.10 | 0,15 | 0.10 | 0,15 | 0.10 |
| Seitenverhältnis von PTH | 14: 1 | 16: 1 | 16: 1 | 18: 1 | 18: 1 | 20: 1 |

| | | | | | | |
|--|---|-----------|-----------|-----------|-----------|-----------|
| N + C + N | 4 + C + 4 | 5 + C + 5 | 5 + C + 5 | 6 + C + 6 | 5 + C + 5 | 6 + C + 6 |
| Beliebige Schichtverbindung | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 |
| Plattenbefüllung über | JA | - | JA | - | JA | - |
| Mindest. Kerndicke (ohne Kupfer) (µm) | 50 | 40 | 40 | 30 | 40 | 30 |
| Mindest. Laserbohrerdurchmesser (µm) | 75 | 65 | 65 | 50 | 50 | 40 |
| Via am begraben Loch / gestapelt über | JA | - | JA | - | JA | - |
| Material | FR4, Megtron, Nelco, Rogers, schweres Kupfer usw. | | | | | |
| Embedded Kondensatorplatine | JA | - | JA | - | JA | - |
| Oberflächenprozess | Bleifreies HASL, ENIG, OSP, Immersionssilber, Immersionszinn, Grelles Gold, Goldfingerüberzug, vorgewählter harter Goldüberzug, Abziehbare Lötmaske, Carbon-Tinte | | | | | |







www.o-leading.com

LED-Leiterplattenhersteller

Unser Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Zertifizierungen

CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE
Certificate No: 18118Q10347R05

We hereby certify that
O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED
Credit No: 61691591-000-07-18-7
Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK
Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 – February 26, 2021
This certificate is invalid without CICC qualified label in the following period

| | | |
|-----------------------------|------------------------------|----------------|
| First supervision and audit | Second supervision and audit | Qualified mark |
|-----------------------------|------------------------------|----------------|

The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn. For the sake of clarity see also the note.






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书
证书号: 18118Q10347R05

兹证明
诚领供应链(香港)有限公司
统一社会信用代码: 61691591-000-07-18-7
注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室
经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

建立的质量管理体系符合
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求


认证范围
印刷线路板的销售

初次获证日期: 2018年02月27日
换证日期: 2019年04月22日
证书有效期: 自2019年04月22日至2021年02月26日
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

| | | |
|-------|-------|-----|
| 第一次监督 | 第二次监督 | 黏贴处 |
|-------|-------|-----|

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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium, Lead, Mercury, Hexavalent Chromium, Sum of PBBs, Monobromobiphenyl, etc. with their respective limits and units.



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
 ROOM 1205, 12/F
 TAI SANG BANK BLDG
 130-132 DES VOEUS ROAD
 CENTRAL, HONG KONG

E490354

| Type | Cond Width | | Cond Thk | SS/ DS/ DSO | Max | Max | | Meets | C | | | |
|--|---------------|---------------|----------------------|-------------|------------|---------------|-----------|-------|-------|-------|-----|---|
| | Min | Edge | | | Area | Solder Limits | Oper Temp | | | Flame | | |
| | mm(in) | mm(in) | mic(mil) | | mm(in) | C | sec | C | Class | UL796 | DSR | I |
| Multilayer (mass laminate) printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-401 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 12.7 (0.5) | 260 | 10 | 130 | V-0 | - | - | |
| O-LEADING-407 | 0.08 (0.003) | 0.2 (0.008) | 17 (0.67) | DS | 9.7 (0.4) | 260 | 10 | 130 | V-0 | All | - | |
| Multilayer printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-408 | 0.125 (0.005) | 0.125 (0.005) | 12 (0.47) Int:136 | DS | 50.8 (2.0) | 280 | 20 | 130 | V-0 | All | * | |
| Single layer printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-002 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 105 | V-0 | All | - | |
| O-LEADING-003 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 130 | V-0 | ▲ | - | |
| O-LEADING-033 | 0.15 (0.006) | 0.3 (0.012) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 10 | 120 | V-0 | All | - | |
| O-LEADING-205 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - | |
| O-LEADING-206 | 0.15 (0.006) | 0.33 (0.013) | 17 (0.67) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - | |
| O-LEADING-D01 | 0.14 (0.006) | 0.15 (0.006) | 33 (1.30) | DS | 25.4 (1.0) | 260 | 10 | 130 | V-0 | All | * | |
| O-LEADING-S01 | 0.25 (0.010) | 0.25 (0.010) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * | |

WIRING, PRINTED - COMPONENT | UL Product iQ

| | | | | | | | | | | | | |
|----------------------|--------------|--------------|-----------|----|------------|-----|---|-----|-----|-----|---|--|
| O-LEADING-S02 | 0.2 (0.008) | 0.2 (0.008) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | HB | ▲ | * | |
| O-LEADING-S03 | 0.25 (0.010) | 0.25 (0.010) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * | |

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



| Quick Turn Lead Time | | |
|----------------------|----------|---------------------|
| Layer Count: | Lead Tim | Special Requirement |
| 1L/2L | 2-3days | 24 Hours,48 Hours |
| 4L | 3-4days | 48 Hours |
| 6L | 4-5days | 72 Hours |
| 8L | 5-6days | NA |
| 10L | 6-7days | NA |
| 12L | 7-8days | NA |
| 14L | 8-9days | NA |

| Standard Lead Time | | |
|--------------------|------------------|------------------------|
| Layer Count: | Sample Lead Time | Volume order lead time |
| 2L | 4 days | 10 days |
| 4L | 5 days | 11 days |
| 6L | 6 days | 12 days |
| 8L | 8 days | 14 days |
| 10L | 10 days | 16 days |
| 12L | 12 days | 18 days |
| 14L | 14 days | 20 days |
| 16-32L | 18 days | 24 days |

Prozessfähigkeit

PCB-Produktionsmöglichkeiten

Schicht Anzahl: 1Layer-32Layer

Fertige Kupferdicke: 1 / 3oz-12oz

Min. Linienbreite / interner Abstand: 3,0 mil / 3,0 mil

Min. Linienbreite / Abstand extern: 4.0mil / 4.0mil

Maximales Seitenverhältnis: 10: 1

Brettstärke: 0.2mm-5.0mm

Max Panel Größe (Zoll): 635 * 1500 mm

Mindestbohrlochgröße: 4mil

Plated Hole Tolerance: +/- 3mil

Blind / Buried Vias (All-Typen): JA

Via Fill (leitend, nicht leitend): JA

Basismaterial: FR-4, FR-4high Tg. Halogenfreies Material, Rogers, Aluminiumbasis,Polyimid,
Schweres Kupfer

Oberflächen: HASL, OSP, ENIG, HAL-LF, Versilberung,Immersiondose, Goldfinger, Kohletinte

SMT-Produktionsmöglichkeiten

Leiterplattenmaterial: FR-4, CEM-1, CEM-3, Leiterplatte auf Aluminiumbasis
Maximale Leiterplattengröße: 510 x 460 mm
Min PCB Größe: 50x50mm
PWB-Stärke: 0.5mm-4.5mm
Brettstärke: 0.5-4mm
Min. Komponentengröße: 0201
Komponente mit Standardchipgröße: 0603 und größer
Maximale Höhe der Komponente: 15 mm
Min. Steigung: 0,3 mm
Min. BGA-Kugelpitch: 0,4 mm
Platzierungsgenauigkeit: +/- 0,03 mm